


### Ferrite Cores



**TDK and EPCOS** the most technically advanced manufacturers in the world


- PC47/PC90/PC95 - Power
- N97/N92/N95 - Power
- HF90/T35 - CMC

**TDG** the largest manufacturer of ferrites in the world

- TP4D/TP4F/TP5B - Power
- TBP22/TPW33 - Power

[mhw-intl.com/ferrite-cores](http://mhw-intl.com/ferrite-cores)

### Powder Cores



The world's largest producer of powder cores.

- Sendust
- MegaFlux
- HighFlux
- MPP

**Core Shapes:**

- Toroids
- EE/ER/EER
- EQ
- Block/Ellipse

[mhw-intl.com/powder-cores](http://mhw-intl.com/powder-cores)

### Nanocrystalline Cores




Premier producer of Nanocrystalline Cores in the world.

Cores for:

- Common Mode Choke
- EMI Filter
- Current Transformer
- Motor Bearing Protection
- Smart Grid Metering
- Noise Spike Killer

[mhw-intl.com/nanocrystalline](http://mhw-intl.com/nanocrystalline)

### Bobbins & Accessories



- Thermoset and Thermoplastic Bobbins from the original TDK tools
- Thermoplastic Bobbins from China
- Thermoset Bobbins from Germany
- Thermoplastic Bobbins from Germany

[mhw-intl.com/bobbins](http://mhw-intl.com/bobbins)

### Soft Magnetics

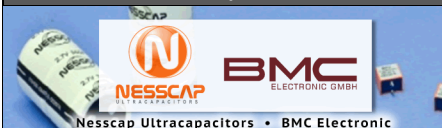


Specialist in supplying non-standard ferrite shapes and sizes as well as non-standard bobbins.

- UU core: 3.0 – 6.0 inch
- EE Core: 3.0 – 8.0 inch
- Toroid: 3.0 – 6.0 inch
- Clamp-on EMI Filters

[mhw-intl.com/non-standard](http://mhw-intl.com/non-standard)

### Ultracapacitors



**Nesscap** premiere producer of Ultracapacitors


- 2.3V and 2.7V
- 3.0F – 6,000F
- Application Modules

**BMC Electronics** specializes in miniaturized Supercapacitors

- Mica Based
- 5.5V
- 0.1F – 0.22F - 0.33F
- 0 - 90% Humidity Rating

[mhw-intl.com/ultracapacitors](http://mhw-intl.com/ultracapacitors)

### Thermal Interface



- Gap Fillers to 6.0 W/mK
- Silicone films to 8.0 W/mK
- Silicone free films to 6.0 W/mK
- Greases silicone and silicone free to 10.0 W/mK
- Double sided thermal tape
- Graphite films to 7.5 and 450.0 W/mK
- All available in die cut pads

[mhw-intl.com/kerafol](http://mhw-intl.com/kerafol)

### Thermal Interface



- Low Silicone gap fillers to 3.0 W/mK
- New Super Soft gap fillers to 3.0 W/mK
- Hybrid Silicone film/gap filler to 3.0 W/mK
- Combination EMI and Thermal Absorber films
- EMI Suppressor films
- All available in die cut pads

[mhw-intl.com/csc-thermal](http://mhw-intl.com/csc-thermal)

### Thermal Interface



**KoolBond**

- Double sided thermal tape
- Available in die cut pads

**Thermal Consulting**

- Custom solutions
- Thermal analysis
- Build prototypes

[mhw-intl.com/koolbond](http://mhw-intl.com/koolbond)